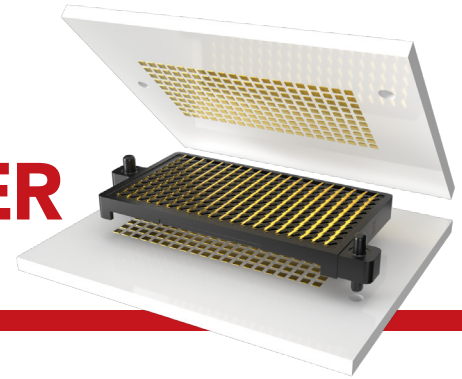


SUPERNOVA[®] LOW PROFILE COMPRESSION INTERPOSER

PAM4
56
Gbps



(1.00 mm) .0394" PITCH • GMI SERIES

SPECIFICATIONS

Insulator Material:
Black LCP
Contact Material:
Copper Alloy
Plating:
Au or 50 μ" (1.27 μm) Ni
Current Rating:
.89 A per pin
(10 pins powered)

GMI

POSITIONS
PER ROW

-10, -20, -30

STYLE

-2
= Dual
Compression

BOARD
SPACING

-1.27
= (1.27 mm) .050"
Board Space

PLATING
OPTION

-G
= 10 μ"
(0.25 μm)
Gold on
contact area

ROWS

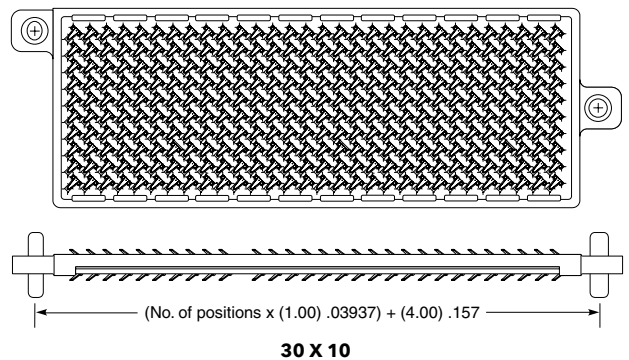
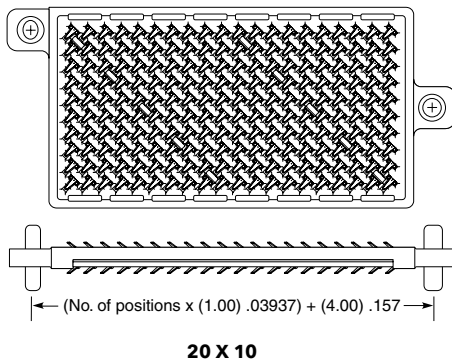
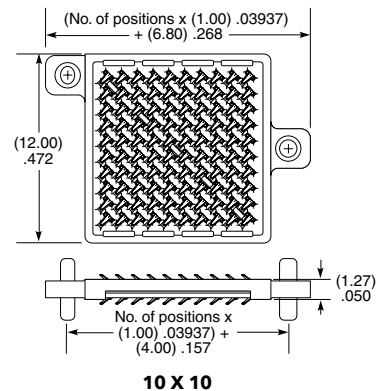
-10
= Ten Rows

PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Complanarity:
(0.05 mm) .002" (10-20)*
(0.08 mm) .003" (30)*
*(.004" stencil solution
may be available;
contact ipg@samtec.com)



GMI Series is an ideal low-cost solution
for board stacking, module-to-board or
LGA interface



Note:
Some lengths, styles and
options are non-standard,
non-returnable